

Regarding the Claim Rejections under 35 U.S.C. § 102

Examiner rejected claims 7-9 under 35 U.S.C. 102 as being anticipated by *Sugano* (JP60200559). With regard to the rejection of claims 7-9, the *Sugano* patent shows substrate or circuit board 30 having packaged chips 2 and 24 disposed along rows of pads on opposite sides of the substrate (Fig. 4).

Applicant's claim 7 recites a **"at least one frame extending along at least each of the opposite sides of the packaged chips\*\*\*"**. *Sugano* does not teach a **"frame extending along the sides of the packaged chips."** Rather, the cited portion of *Sugano* shows chips mounted on opposite sides of a substrate 30. The *Sugano* substrate is not a frame. Further, the *Sugano* substrate does not extend along the sides of the packaged chips. The depicted packaged chips 2 and 24 in *Sugano* are mounted to the substrate with the substrate being beneath the packaged packaged chips, not along the sides.

Applicants therefore respectfully submit that the rejection under *Sugano* is improper and should be withdrawn.

With regard to the Applicant's new claims, the claims are directed to a chip stack supported by the original specification and therefore correction is made to the error previously identified by the applicant in the reissue declaration and no new declaration is needed.


Summary

In response to Examiner's request, Applicant's resubmit the Information Disclosure Statement. Further, Applicants present arguments regarding the Examiner's 102 rejections. Applicants thank the Examiner for indication of allowance for Applicants claims 1-6. Please contact the undersigned with any questions regarding this Application or Response.

Respectfully submitted,

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